Title of Invention: A SYSTEM AND METHOD FOR CONVEYING AND INSPECTING SEMICONDUCTOR PACKAGE

ABSTRACT

Embodiments of the present invention generally relate to the field of semiconductor, in particular to a system (1) and method (1300) for conveying and inspecting semiconductor package. More particularly, the present invention relates to the post-seal inspection system (1) and method (1300) that performs automatic conveyance of semiconductor package for inspection process.

(The most illustrative figure is FIG. 1)